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ASX RELEASE **25 March 2025**

ASX: NVU

Pitt Street Research Semiconductor Conference Presentation

Nanoveu Limited (ASX: NVU, OTCQB: NNVUF) ("Nanoveu" or the "Company"), a technology innovator across advanced semiconductor, visualisation, and materials science, is pleased to advise of its participation today at the Pitt Street Research Semiconductor Conference 2026.

Nanoveu's Director and EMASS founder, Dr Mohamed Sabry, will be presenting the Company's strategy for progressing its EMASS semiconductor business. Attached is the presentation that Dr Sabry will be speaking to at the conference.

This announcement has been authorised for release by the Board of Directors.

-ENDS-

Nanoveu Media
Alfred Chong, Nanoveu MD and CEO
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About Nanoveu Limited

Further details on the Company can be found at https://nanoveu.com/.

EMASS is a pioneering technology company specialising in the design and development of advanced systems-on-chip (SoC) solutions. These SoCs enable ultra-low-power, AI-driven processing for smart devices, IoT applications, and 3D content transformation. With its industry-leading technology, EMASS will enhance Nanoveu's portfolio, empowering a wide range of industries with efficient, scalable AI capabilities, further positioning Nanoveu as a key player in the rapidly growing 3D content, AI and edge computing markets.

EyeFly3D™ is a comprehensive platform solution for delivering glasses-free 3D experiences across a range of devices and industries. At its core, EyeFly3D™ combines advanced screen technology, sophisticated software for content processing, and now, with the integration of EMASS's ultra-low-power SoC, powerful hardware.

Nanoshield™ is a self-disinfecting film that uses a patented polymer of embedded Cuprous nanoparticles to provide antiviral and antimicrobial protection for a range of applications, from mobile covers to industrial surfaces. Applications include *Nanoshield™ Marine*, which prevents the growth of aquatic organisms on submerged surfaces like ship hulls, and *Nanoshield™ Solar*, designed to prevent surface debris on solar panels, thereby maintaining optimal power output.

Forward Looking Statements This announcement contains 'forward-looking information' that is based on the Company's expectations, estimates and projections as of the date on which the statements were made. This forward-looking information includes, among other things, statements with respect to the Company's business strategy, plans, development, objectives, performance, outlook, growth, cash flow, projections, targets and expectations and related expenses. Generally, this forward-looking information can be identified by the use of forward-looking terminology such as 'outlook', 'ambition', 'anticipate', 'project', 'target', 'potential', 'likely', 'believe', 'estimate', 'expect', 'intend', 'may', 'mission', 'would', 'could', 'should', 'scheduled', 'will', 'plan', 'forecast', 'evolve' and similar expressions. Persons reading this announcement are cautioned that such statements are only predictions, and that the Company's actual future results or performance may be materially different. Forward-looking information is subject to known and unknown risks, uncertainties and other factors that may cause the Company's actual results, level of activity, performance, or achievements to be materially different from those expressed or implied by such forward looking information.

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Pitt Street Research Semiconductor Conference 2026

PITT STREET RESEARCH

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AUTHORISATION This document has been authorised for release by the Company's Board of Directors.

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Capital Structure

Nanoveu Share Price

ASX - AUD

Nanoveu Limited (NVU.AX)

1D 5D 1M 6M YTD 1Y 5Y All

Capital Structure

ASX/OTCQB Code	NVU/NNVUF
Q4 2025 Cash	$1.8m
Cap Raise Jan 2026	$7.5m
Shares on Issue	1,080.4m
Options on Issue	269.9m
Average Volume	8.5m
Market Cap	$68.07m
Previous Close[1]	$0.063

1. As at close 23 March '26.

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Board and Management

Dr. David Pevcic

Executive Chairman

- Experienced professional and investor in the resources and technology sector
- Non-Executive Chairman at Battery Age Minerals Ltd (ASX: BM8)
- Non-Executive Chairman at Infini Resources Ltd (ASX: I88)
- Holds a Bsc, MBBS, from the university of Western Australia

Dr. Mohamed Sabry

EMASS Founder and Director

- CTO, Founder of EMASS
- Associate Professor, NTU Singapore
- Postdoc at Stanford Univeristy
- Recipient of Nanyang Education Award
- Ph.D. from EPFL

Alfred Chong

Group CEO and Director

- Founder of Nanoveu, has 30+ years of experience in scaling companies and trade sales
- Former CEO of Atex Media Command (APAC), THISS Technologies, 121View
- Former CMO at 3D International

Steve Apedaile

Non-Executive Director

- 30 years of experience in accounting
- Worked at KPMG and Horwath Hong Kong
- Fellow of the ICAEW and Member of the AICD.
- Executive Chairman of Sprintex (ASX:SIX)

Raymond Chen

CFO and Director

- Held roles at Iluka Resources, NRW Holdings, Equinox Resources and KPMG
- MBA, University of Cambridge (Judge Business School)
- 15+ years' experience across resources and corporate finance

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Semiconductor Leadership Team

Mark Goranson

CEO of Semiconductor Technology

- VP of Global Ops, TE Connectivity
- SVP of Fab Ops, ON Semi
- VP of Fab Ops, Freescale
- Early Member of Intel

Dr. Mohamed Sabry

CTO, Founder of EMASS

- Associate Professor, NTU Singapore
- Postdoc, Stanford
- Recipient of Nanyang Education Award
- Ph.D. from EPFL

Scott Smyser

VP, Sales & Marketing

- EVP Marketing & BD, Si-Ware Systems
- VP & GM, VTI Technologies (Murata)
- SVP Sales, Atomica
- SVP Strategic Sales, Rockley Photonics

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EMASS Introduction

Fabless Semiconductor Innovator in Edge AI Processing

- Ultra-low-power Edge AI SoCs for always-on intelligence in battery constrained devices
- Flagship ECS-DoT chip up to 20x more energy efficient than peers
- Usable across drones, wearables, IoT devices and other Edge AI applications

Established Global Operations

- Global operations and R&D center's in USA, Singapore and Egypt
- 100% of EMASS acquired by Nanoveu Limited (ASX:NVU), March 2025

Expert Team Across Disciplines

- Deep expertise in AI/ML, neural network acceleration, semiconductor design, sensor fusion, and embedded systems
- Experienced management with semiconductor and AI industry backgrounds

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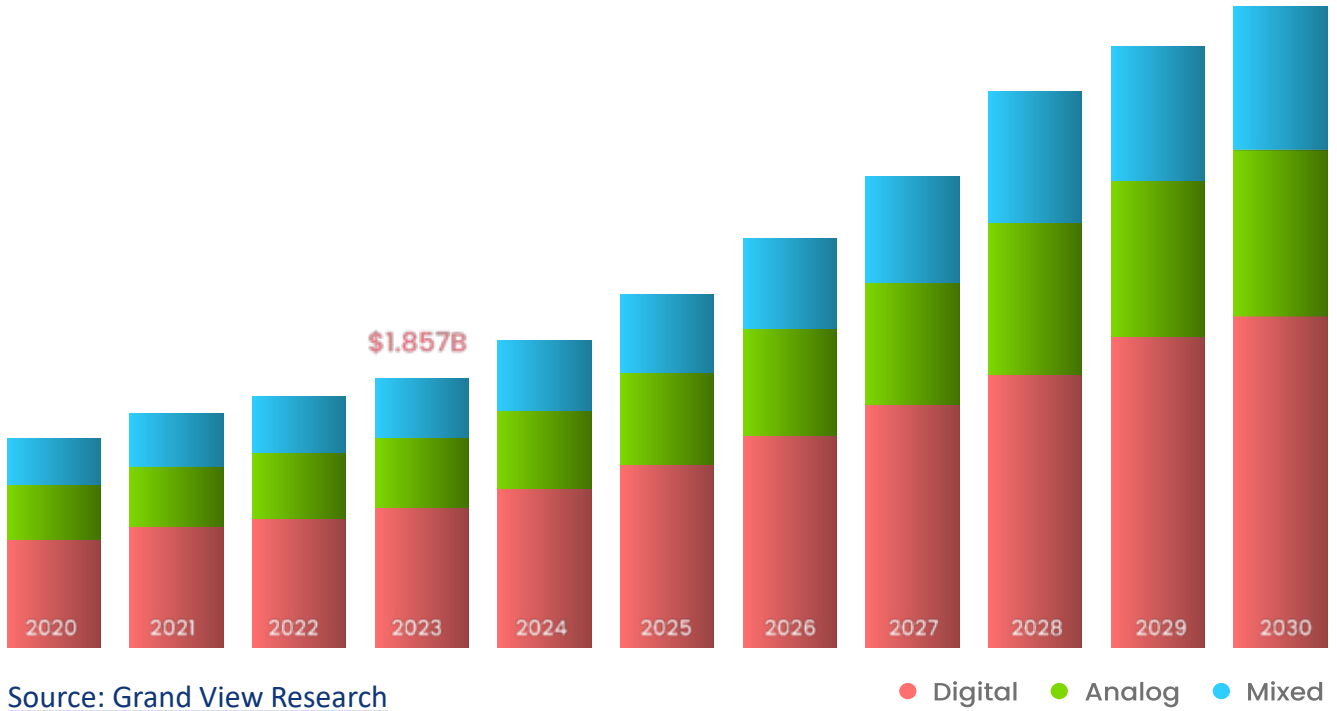
Semiconductor & SoC Market Opportunity

System On Chip Market Size

By Type 2020-2030 (USD Billion)



Source: Grand View Research

SoC Market Growth:

Applications demanding continuous sensing, context awareness, and real-time decision-making

Set to hit

$325.7B by 2030

8.5% Global Market CAGR

Driven by AI, 5G, and smart devices.

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Revolutionising Edge AI

Edge AI Opportunities

- Robust AI models require increased computation power and battery
- Current chips are not designed for efficient edge AI use cases
- Devices need versatile chips with multi-sensor use-cases

EMASS Solution

- Executes AI inference directly at the sensor under 1 mW power
- Provides up to 20x energy efficiency vs leading chips
- Enables smaller, lower-cost, and reconfigurable designs across drones, IoT, and wearables

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Target Edge AI Sectors

Hearables

$USD 138.5B by 2029

Source: Marketsandmarkets

Wearables

$USD 368.4B by 2035

Source: Fact.MR

AI Cameras

$USD 22.1B by 2028

Source: Marketsandmarkets

IoT Sensory

$USD 168.69B by 2030

Source: Mordor Intelligence

AR Glasses

$USD 8.26B by 2030

Source: Grand View Reasearch

Drones

$USD 223.66B by 2034

Source: Fact.MR

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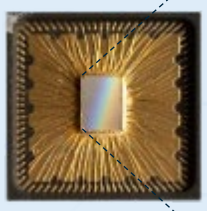
Redefining What's Possible
in Ultra-Low-Power Edge AI

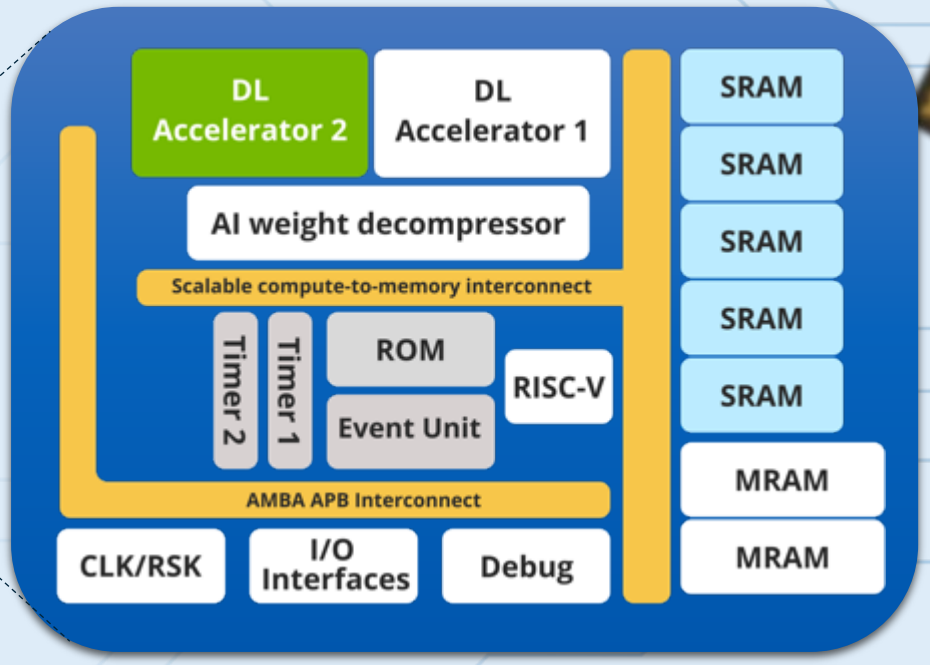
Fully Programmable System on Chip (SoC)

- Processor
- AI engines
- IPs for compressed AI

Local decision-making at the Edge

- Always-on AI Inference
- Sensor fusion
- Support CNNs, ML, Data Processing, etc.





Key Architecture Features

- <1 to 5 mW power consumption (Avg 2mW always on)
- No External DRAM needed (very fast on-chip SRAM and nonvolatile MRAM/RRAM)
- SW and HW support for highly compressed AI workloads

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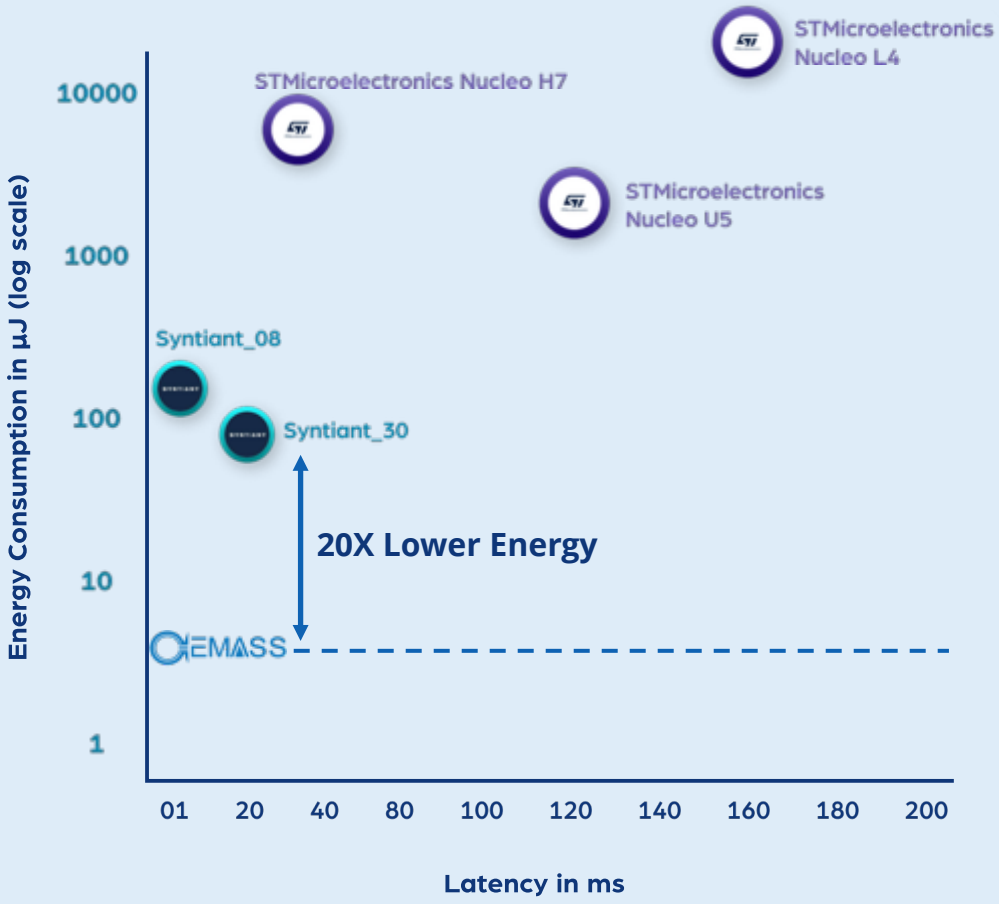
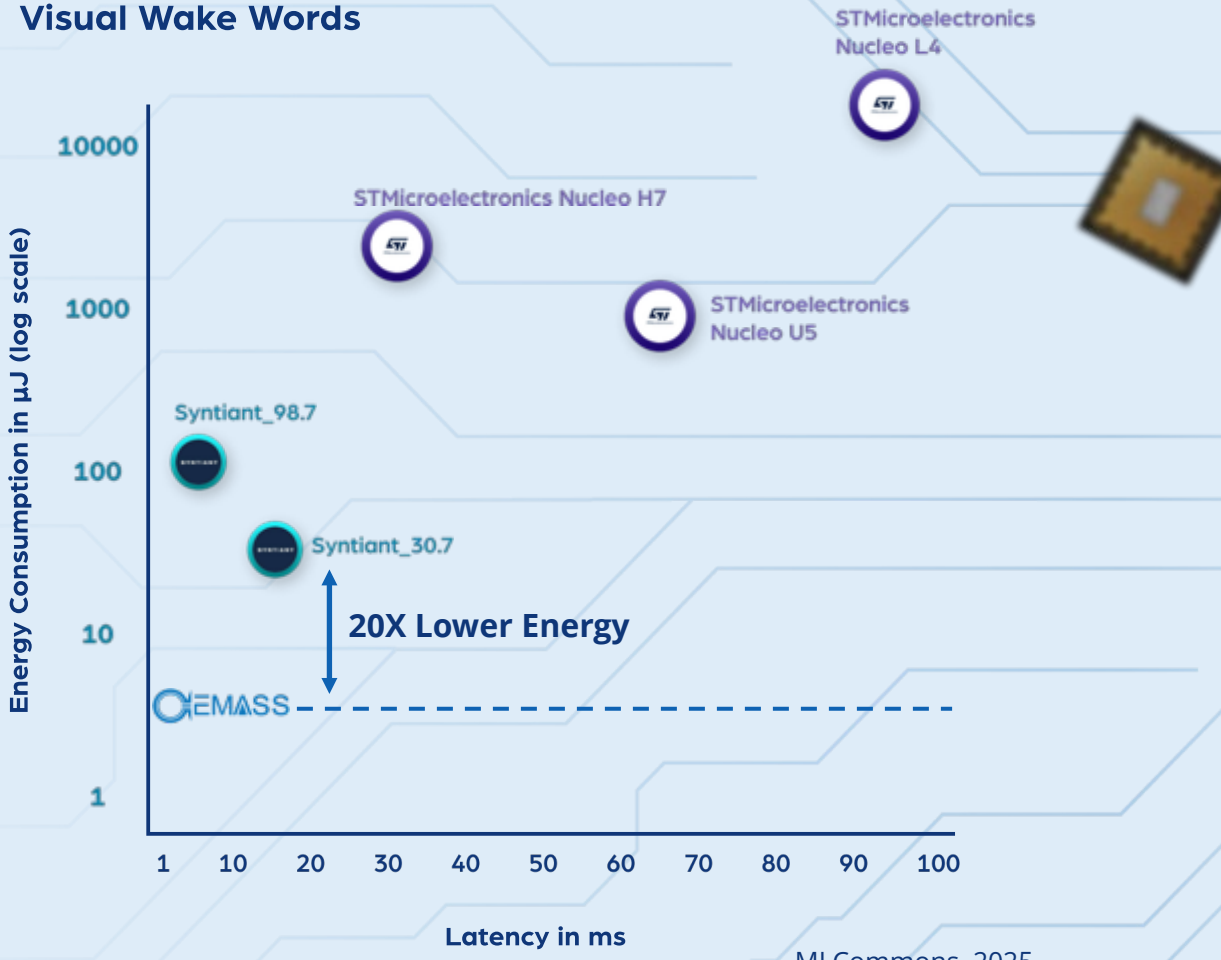
Exceptional AI Computation

20X Lower Energy

Image Classification



Visual Wake Words



MLCommons, 2025

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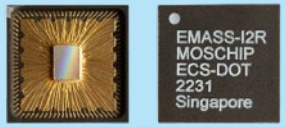
Breakthrough in Drone Endurance

Longer Flight Times

+60% increase in flight time without any hardware changes

AI Ready Platform

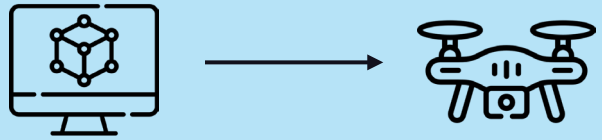
Enables onboard intelligence for mission-critical use cases



- Precision Landing
- Predictive Maintenance

Live Trials Underway

Bridging simulation to reality. Results expected in April 2026



How it works

Real-time control @ 50hz executing full “sense-think-act” loop every 20ms

Operates in sub-milliwatt power envelope

AI engines include:

- Surrogate power predictor (25% drop in overthrust)
- Reinforcement learning controller (improves distance per Watt by 20%)

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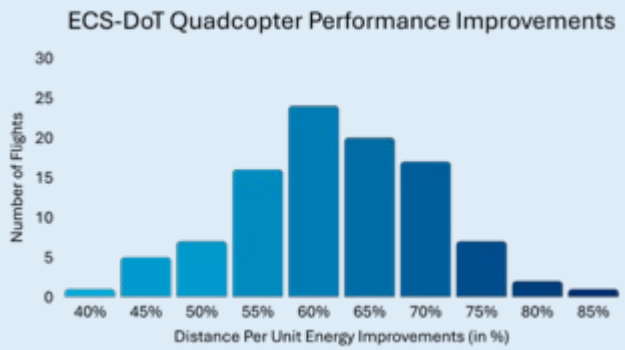
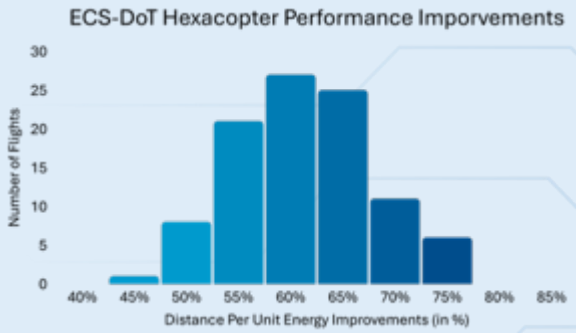
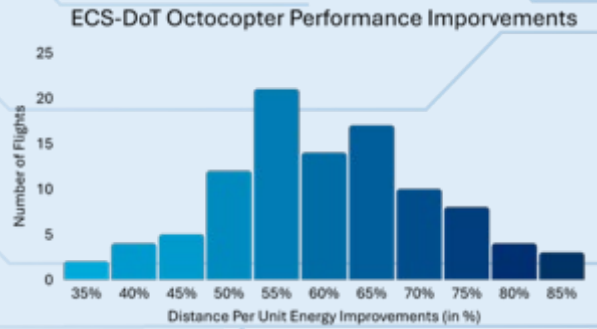
ECS-DoT Achieves Major Drone Performance Gains

Drone Type	Quadcopter	Hexacopter	Octocopter
Graph			
Use-cases	• Consumer • Enterprise	• Agriculture • Logistics • Terrain Mapping	• Industrial inspection • Defense • Professional
Performance Gains	Achieved up **to 80% improvement** in mission endurance, with a **60% average** extended flight time over baseline	Delivered up to **75% improvement** in flight endurance, with an average	Delivered consistent flight **endurance up to 85% with an average 57%** improvement

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Live Drone Trials Update

Status update:

Live drone data log captured

AI model trained with live drone data

ECS-DoT Hardware integration with the drone

Performing Hardware-in-the-loop testing with custom simulator provided by partner

Expected live drone trials March end- April 2026

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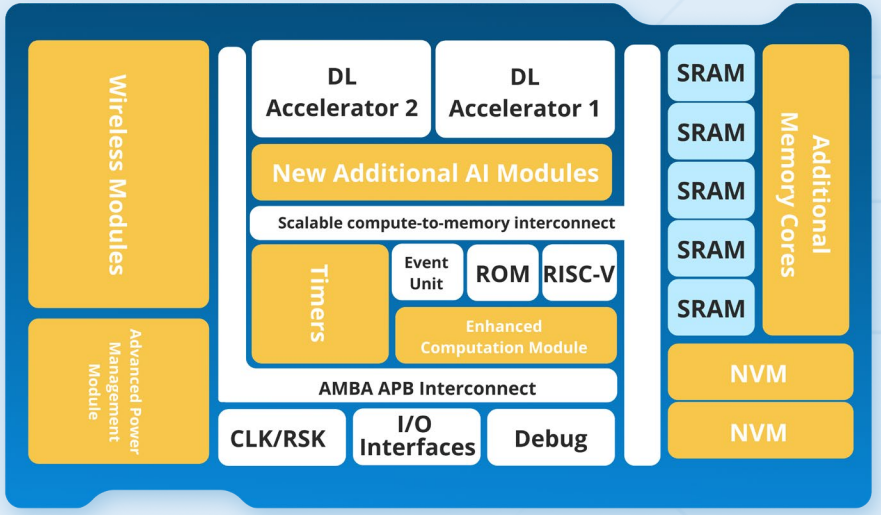
Next Generation ECS-DoT-16

Strengthening Leadership in Ultra-Low-Power Edge AI



Enhancement Highlights

- Fully integrated Low Energy Bluetooth (BLE)
- New Adaptive Power Management
- Dedicated AI module for object detection
- Expanded on-chip memory
- Integrated Floating-Point Unit (FPU)

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Next Generation ECS-DoT 16nm

Enhancement Benefits

Dedicated AI Acceleration Module for Object Detection

- YOLO (You Only Look Once)-Nano-class architectures;
- MobileNet-SSD style detection heads; and
- FOMO (Faster Objects, More Objects)-style event and object detectors

New Adaptive Fine-Grained Power-Management Architecture

- Dynamic clock gating for workload-aware optimization
- Autonomous low-power states
- Microsecond-level sleep/wake

Integrated Floating-Point Unit (FPU)

- Accelerate DSP
- Enable mixed-precision AI workflows
- Improved developer experience

Integrated Bluetooth Low Energy Subsystem (Analog + RF)

- Eliminates external wireless ICs
- Reduces board area, BOM, and design complexity

Expanded On-chip Memory

- Support larger/complex neural networks
- Reduce off-chip memory

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Award Winning SoC Performance

ECS-DoT won best in show for AI and Machine Learning

- At two of the largest shows in the industry – CES & embedded world
- Major accolades for innovative architecture and superior performance
- Ultra-low-power, RISC-V based SoC delivering real-time edge AI processing for vision, audio, and sensor data
- Showcased multiple demos with ECS-DoT including: predictive maintenance, audio security detection, wrist-worn wearable and bond-conduction audio

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Strong Commercial Momentum

Customer & Partner Engagements

OEM engagements – eval boards shipped

- Wearables – AR glasses, hearables
- Dash cam
- Predictive maintenance

Partner collaborations – reference designs

- Inertial sensors
- Image sensors
- Spectral sensors

Select commercial partners/collaborators

What the Market is Responding To

Ultra-low power AI inference

- < 10 ms vs. 150-300 ms for competitors
- Up to 20X lower energy consumption vs. competitors

AI Model Portability

- Supports a wide range of AI Models
- Fast and easy development cycle
- Interoperability

Multi Sensor Integration

- Seamless integration with a variety of sensor types
- Real-time fusion of audio, motion and environmental data

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Arrow Electronics Collaboration

Arrow Electronics (NYSE: ARW)

- Global technology distributor and engineering partner
- 2024 global sales of US$28 billion

Collaboration with EMASS

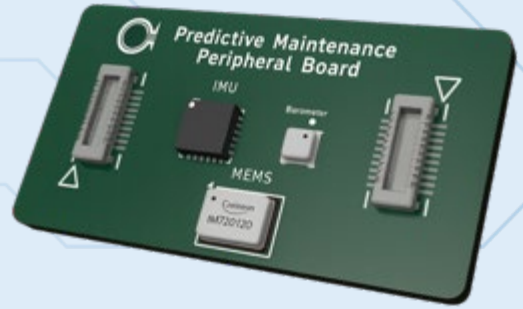
- Enhanced SDKs, developer tools, reference designs

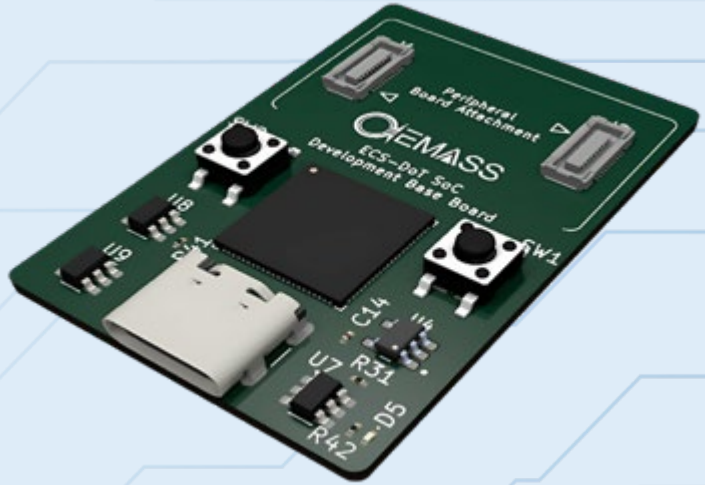
Predictive maintenance first reference design

- Cold asset tracking next design

Comarketing to customers

- Expand customer reach and engagement





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Ref announcement 29 Oct 2025. Arrow Electronics Fact Sheet 6 Feb 25.

Semtech Collaboration

Semtech Corporation (Nasdaq: SMTC)

- Global semiconductor provider
- 2024 global sales of US$800 million plus

Collaboration with EMASS

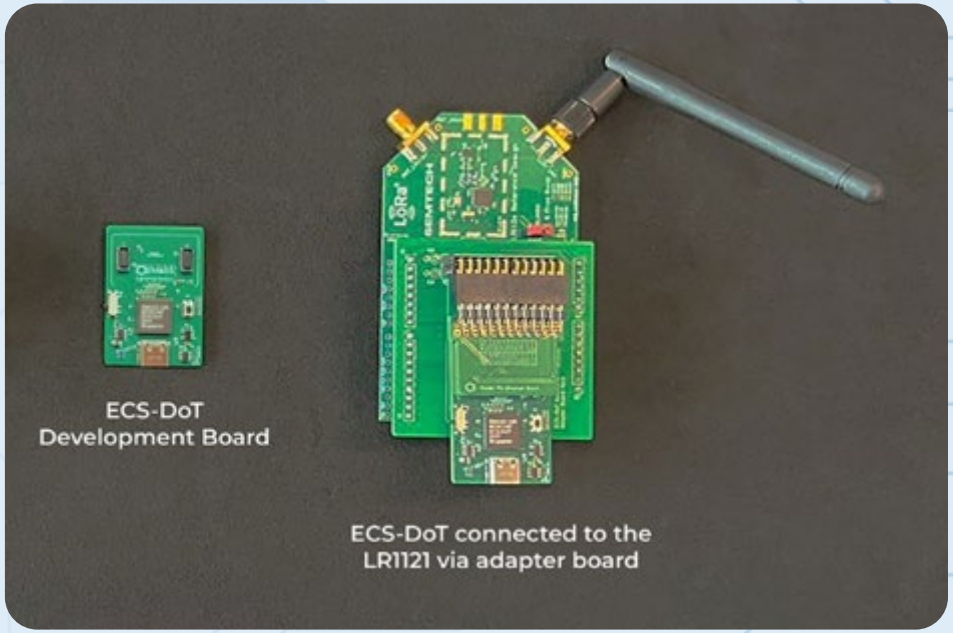
- Combine Semtech's LoRaWAN wireless transceiver with ECS-DoT (demo showcased at CES 2026)

Reference designs

- Predictive maintenance
- Security detection

Comarketing to customers

- Expand customer reach and engagement



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Ref announcement 9 Dec 2025.
Semtech Fourth Quarter and Fiscal Results 2024.

Advancing Hearables

Reference design integrating STMicroelectronics inertial sensing with EMASS ECS-DoT

ECS-DoTs Highlights on the Reference Design

Sub-10ms

Local inference means voice commands are acted on in real time.

No Cloud

Keyword recognition runs entirely on-device, eliminating latency

Always-on

Motion-triggered wake-up ensures extended battery runtime significantly

Validated

The reference design gives product teams a fast-track path to integration

Key Reference Design Details

Design Part	Details
Processor	ECS-DoT edge-AI SoC (RISC-V based, sub-milliwatt operation)
Sensor	ST LSM6DSV16BX MEMS IMU — detects jaw movement to trigger wake-up
Function	Always-on keyword spotting via bone-conduction audio
Pipeline	Motion-triggered activation → on-device audio classification → keyword recognition

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Scaling Commercial Operations

USA

Continued Customer Engagement

- Added sales director & field applications engineer
- Continued OEM engagement

EU

Setting up EU Operations

- Sales director
- New distribution partner

Asia

Application-Led Engagement

- Added sales rep
- New distribution partner

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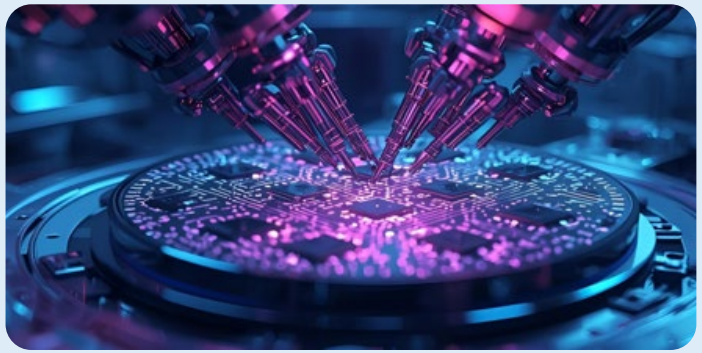
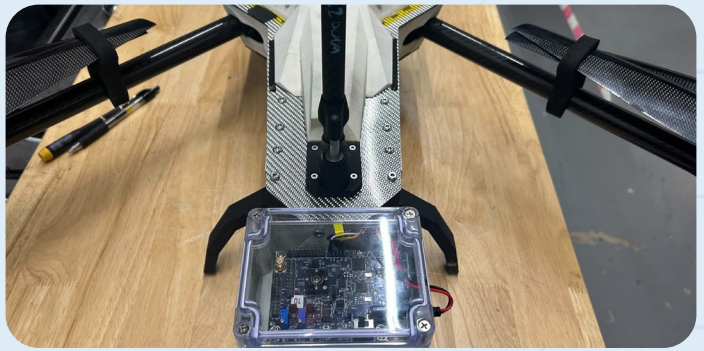
Upcoming Technical Catalysts



ECS-DoT 16nm and beyond

- Strengthening leadership in ultra-low-power Edge AI
- Integration of key chip enhancements
- Designed to further reduce power consumption while supporting larger and more complex AI models



Live-drone flight validation

- Validate performance gains from simulations
- Assess power consumption, latency, and endurance in live flight conditions

Drone Technology Expansion

- Building on recent drone technology licensing
- Developing integrated edge AI solutions for the broader drone ecosystem
- Positioning for high-growth drone markets

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Upcoming Commercial Catalysts

Expanding Use-cases and Environments for ECS-DoT

- Improvements across evaluations and demos with ECS-DoT including:
  - Predictive maintenance
  - Security detection
  - Wrist-worn wearable
  - Cold asset tracking

More partner engagements

- Reference designs with ECS-DoT
- Comarketing
- Easier customer adoption

Targeting First Sales of ECS-DoT in 2026

- OEMs with eval boards
- Design-in process started
- More customer demand

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Thank You

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